

74LCX74

Low Voltage Dual D-Type Positive Edge-Triggered Flip-Flop with 5V Tolerant Inputs

Features

- 5V tolerant inputs
- 2.3V–3.6V V_{CC} specifications provided
- 7.0ns t_{PD} max. ($V_{CC} = 3.3V$), $10\mu A$ I_{CC} max.
- Power down high impedance inputs and outputs
- $\pm 24mA$ output drive ($V_{CC} = 3.0V$)
- Implements proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Leadless Pb-Free DQFN package

General Description

The LCX74 is a dual D-type flip-flop with Asynchronous Clear and Set inputs and complementary (Q , \bar{Q}) outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

Asynchronous Inputs:

- LOW input to \bar{S}_D (Set) sets Q to HIGH level
- LOW input to \bar{C}_D (Clear) sets Q to LOW level
- Clear and Set are independent of clock
- Simultaneous LOW on \bar{C}_D and \bar{S}_D makes both Q and \bar{Q} HIGH


Ordering Information

Order Number	Package Number	Package Description
74LCX74M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LCX74SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX74BQX ⁽¹⁾	MLP14A	14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm
74LCX74MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Note:

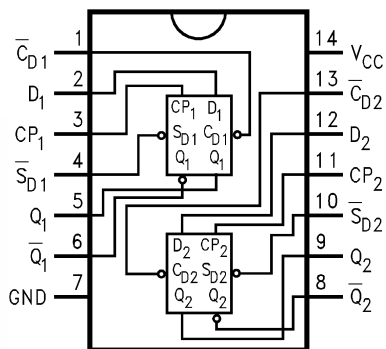
1. DQFN package available in Tape and Reel only.

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

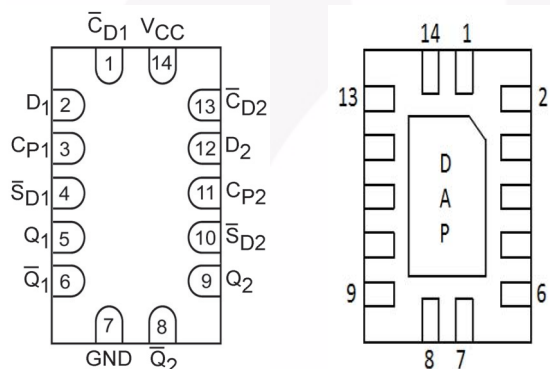
 All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagrams

Pin Assignments for SOIC, SOP, and TSSOP



Pad Assignment for DQFN



(Top View)

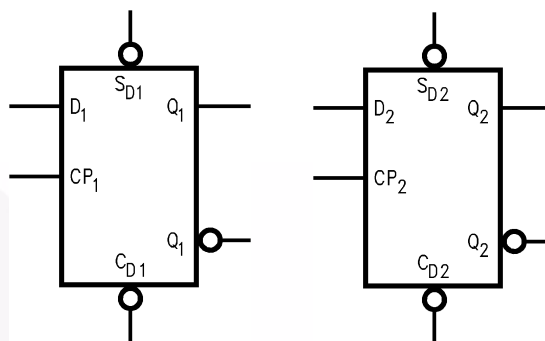
(Bottom View)

Pin Description

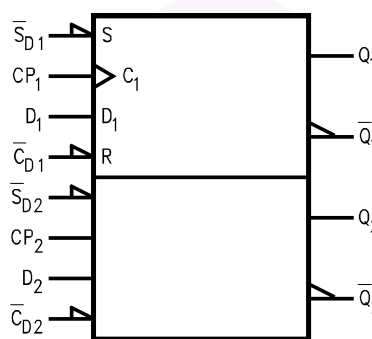
Pin Names	Description
D ₁ , D ₂	Data Inputs
CP ₁ , CP ₂	Clock Pulse Inputs
C _{D1} , C _{D2}	Direct Clear Inputs
S _{D1} , S _{D2}	Direct Set Inputs
Q ₁ , Q ₁ $\bar{}$, Q ₂ , Q ₂ $\bar{}$	Outputs
DAP	No Connect

Note: DAP (Die Attach Pad)

Logic Symbols



IEEE/IEC



Truth Table

(Each Half)

Inputs				Outputs	
S _D	C _D	CP	D	Q	Q $\bar{}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H	H
H	H	↗	H	H	L
H	H	↘	L	L	H
H	H	L	X	Q ₀	Q ₀ $\bar{}$

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial

↗ = LOW-to-HIGH Clock Transition

Q₀(Q₀ $\bar{}$) = Previous Q(Q $\bar{}$) before LOW-to-HIGH Transition of Clock

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	-0.5V to +7.0V
V_I	DC Input Voltage	-0.5V to +7.0V
V_O	DC Output Voltage, Output in HIGH or LOW State ⁽²⁾	-0.5V to $V_{CC} + 0.5V$
I_{IK}	DC Input Diode Current, $V_I < GND$	-50mA
I_{OK}	DC Output Diode Current $V_O < GND$	-50mA
	$V_O > V_{CC}$	+50mA
I_O	DC Output Source/Sink Current	$\pm 50mA$
I_{CC}	DC Supply Current per Supply Pin	$\pm 100mA$
I_{GND}	DC Ground Current per Ground Pin	$\pm 100mA$
T_{STG}	Storage Temperature	-65°C to +150°C

Note:

2. I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions⁽³⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Supply Voltage Operating	2.0	3.6	V
	Data Retention	1.5	3.6	
V_I	Input Voltage	0	5.5	V
V_O	Output Voltage, HIGH or LOW State	0	V_{CC}	V
I_{OH} / I_{OL}	Output Current $V_{CC} = 3.0V-3.6V$		± 24	mA
	$V_{CC} = 2.7V-3.0V$		± 12	
	$V_{CC} = 2.3V-2.7V$		± 8	
T_A	Free-Air Operating Temperature	-40	85	°C
$\Delta t / \Delta V$	Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$	0	10	ns/V

Note:

3. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	Conditions	T _A = -40°C to +85°C		Units
				Min.	Max.	
V _{IH}	HIGH Level Input Voltage	2.3–2.7		1.7		V
		2.7–3.6		2.0		
V _{IL}	LOW Level Input Voltage	2.3–2.7			0.7	V
		2.7–3.6			0.8	
V _{OH}	HIGH Level Output Voltage	2.3–3.6	I _{OH} = -100μA	V _{CC} - 0.2		V
		2.3	I _{OH} = -8mA	1.8		
		2.7	I _{OH} = -12mA	2.2		
		3.0	I _{OH} = -18mA	2.4		
			I _{OH} = -24mA	2.2		
V _{OL}	LOW Level Output Voltage	2.3–3.6	I _{OL} = 100μA		0.2	V
		2.3	I _{OL} = 8mA		0.6	
		2.7	I _{OL} = 12mA		0.4	
		3.0	I _{OL} = 16mA		0.4	
			I _{OL} = 24mA		0.55	
I _I	Input Leakage Current	2.3–3.6	0 ≤ V _I ≤ 5.5V		±5.0	μA
I _{OFF}	Power-Off Leakage Current	0	V _I or V _O = 5.5V		10	μA
I _{CC}	Quiescent Supply Current	2.3–3.6	V _I = V _{CC} or GND		10	μA
			3.6V ≤ V _I ≤ 5.5V		±10	
ΔI _{CC}	Increase in I _{CC} per Input	2.3–3.6	V _{IH} = V _{CC} - 0.6V		500	μA

AC Electrical Characteristics

Symbol	Parameter	T _A = -40°C to +85°C, R _L = 500Ω						Units
		V _{CC} = 3.3V ± 0.3V, C _L = 50pF		V _{CC} = 2.7V, C _L = 50pF		V _{CC} = 2.5V ± 0.2V, C _L = 30pF		
		Min.	Max.	Min.	Max.	Min.	Max.	
f _{MAX}	Maximum Clock Frequency	150		150		150		MHz
t _{PHL} , t _{PLH}	Propagation Delay, CP _n to Q _n or \overline{Q}_n	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{PHL} , t _{PLH}	Propagation Delay, \overline{C}_Dn or \overline{S}_Dn to Q _n or \overline{Q}_n	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _S	Setup Time	2.5		2.5		4.0		ns
t _H	Hold Time	1.5		1.5		2.0		ns
t _W	Pulse Width CP	3.3		3.3		4.0		ns
t _W	Pulse Width and \overline{C}_D , \overline{S}_D	3.3		3.6		4.0		ns
t _{REC}	Recovery Time	2.5		3.0		4.5		ns
t _{OSHL} , t _{OSLH}	Output to Output Skew ⁽⁴⁾		1.0					ns

Note:

4. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	V_{CC} (V)	Conditions	$T_A = 25^\circ\text{C}$	
				Typical	Unit
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	3.3	$C_L = 50\text{pF}$, $V_{IH} = 3.3\text{V}$, $V_{IL} = 0\text{V}$	0.8	V
		2.5	$C_L = 30\text{pF}$, $V_{IH} = 2.5\text{V}$, $V_{IL} = 0\text{V}$	0.6	
V_{OLV}	Quiet Output Dynamic Valley V_{OL}	3.3	$C_L = 50\text{pF}$, $V_{IH} = 3.3\text{V}$, $V_{IL} = 0\text{V}$	-0.8	V
		2.5	$C_L = 30\text{pF}$, $V_{IH} = 2.5\text{V}$, $V_{IL} = 0\text{V}$	-0.6	

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = \text{Open}$, $V_I = 0\text{V}$ or V_{CC}	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3\text{V}$, $V_I = 0\text{V}$ or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3\text{V}$, $V_I = 0\text{V}$ or V_{CC} , $f = 10\text{MHz}$	25	pF

AC Loading and Waveforms (Generic for LCX Family)

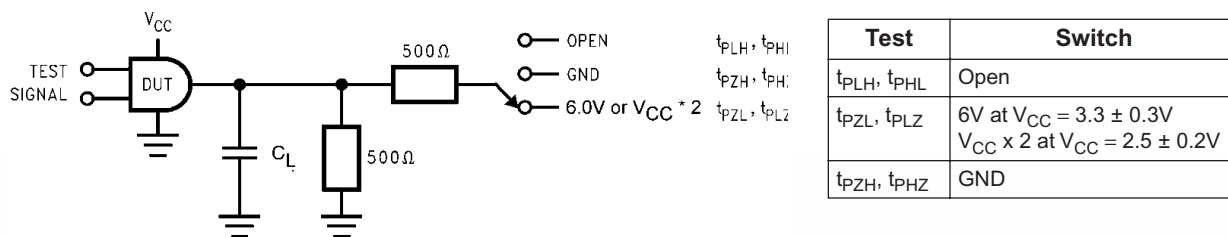
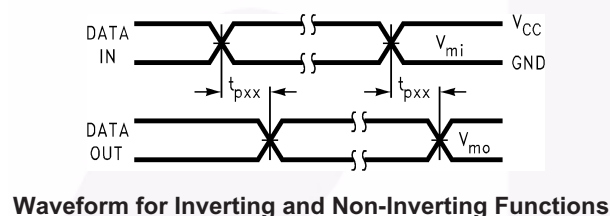
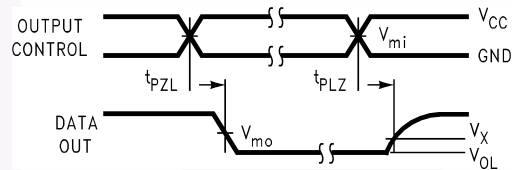


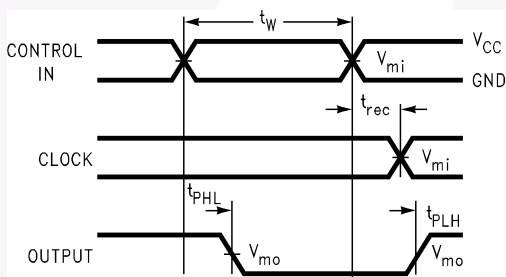
Figure 1. AC Test Circuit (C_L includes probe and jig capacitance)



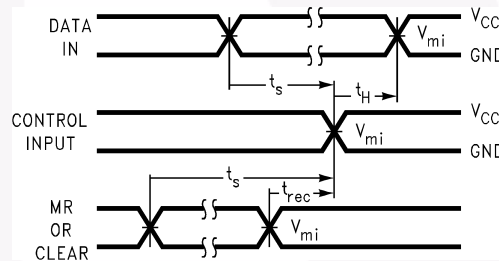
Waveform for Inverting and Non-Inverting Functions



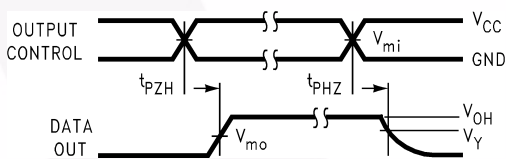
3-STATE Output Low Enable and Disable Times for Logic



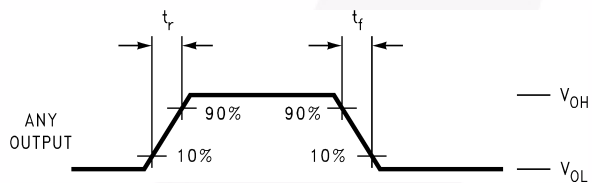
Propagation Delay, Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output High Enable and Disable Times for Logic

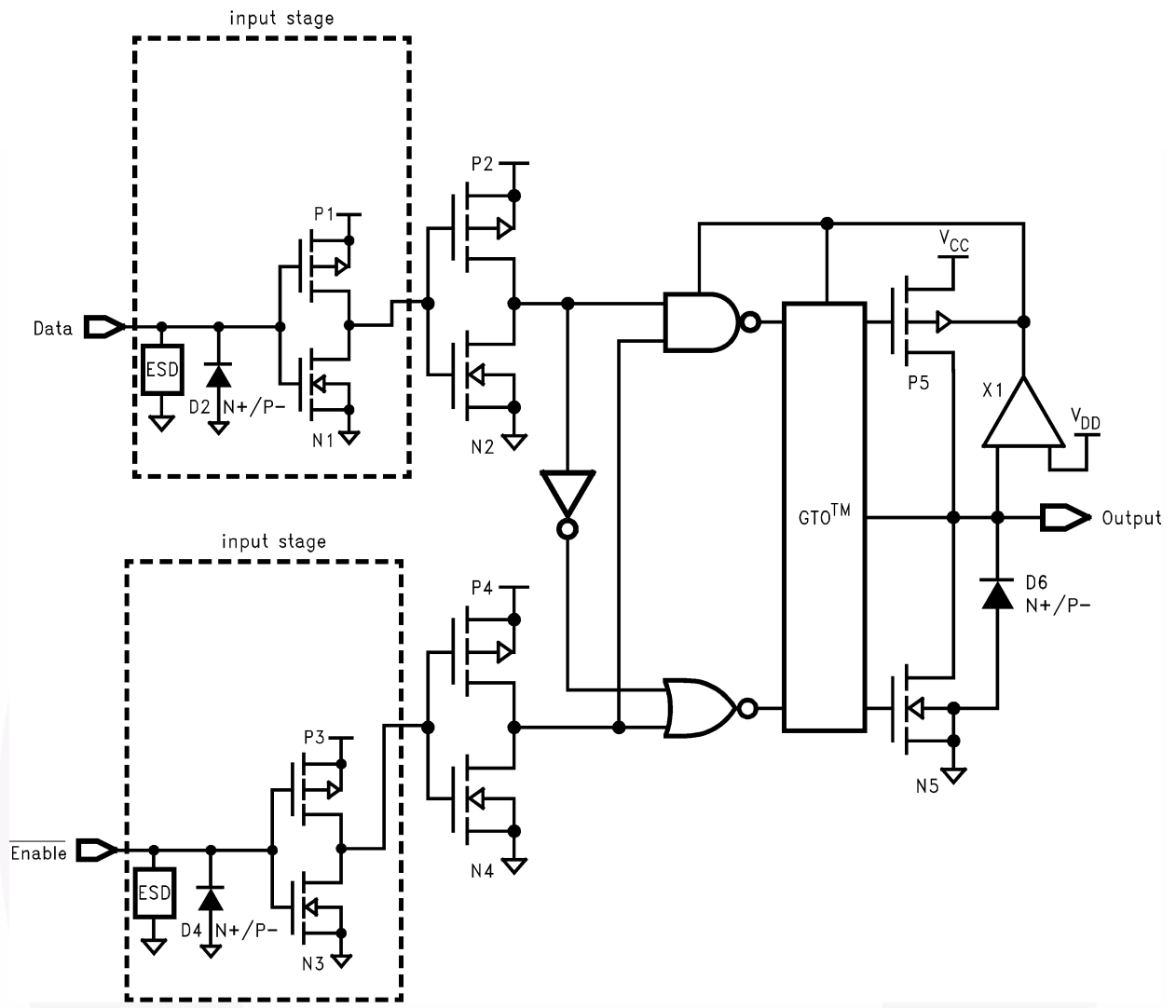


t_{rise} and t_{fall}

Symbol	V_{CC}		
	$3.3V \pm 0.3V$	2.7V	$2.5V \pm 0.2V$
V_{mi}	1.5V	1.5V	$V_{CC}/2$
V_{mo}	1.5V	1.5V	$V_{CC}/2$
V_x	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
V_y	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$

Figure 2. Waveforms (Input Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

Schematic Diagram (Generic for LCX Family)

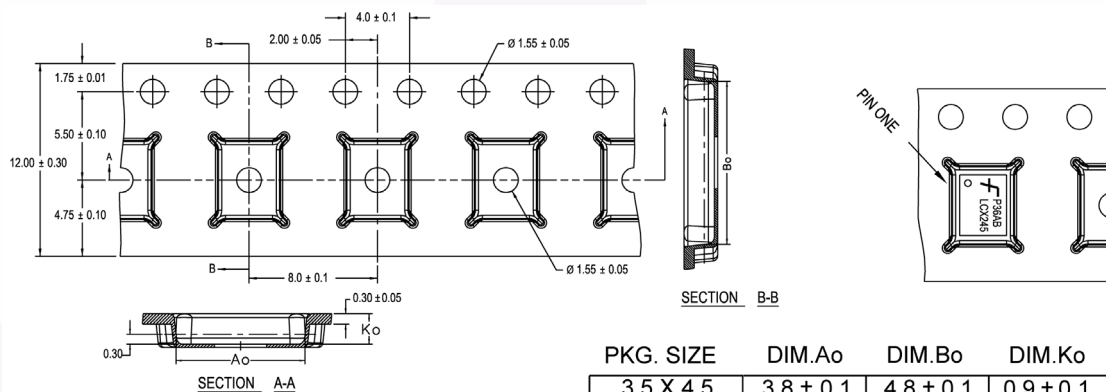


Tape and Reel Specification

Tape Format for DQFN

Package Designator	Tape Section	Number of Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (Typ.)	Empty	Sealed
	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typ.)	Empty	Sealed

Tape Dimensions inches (millimeters)



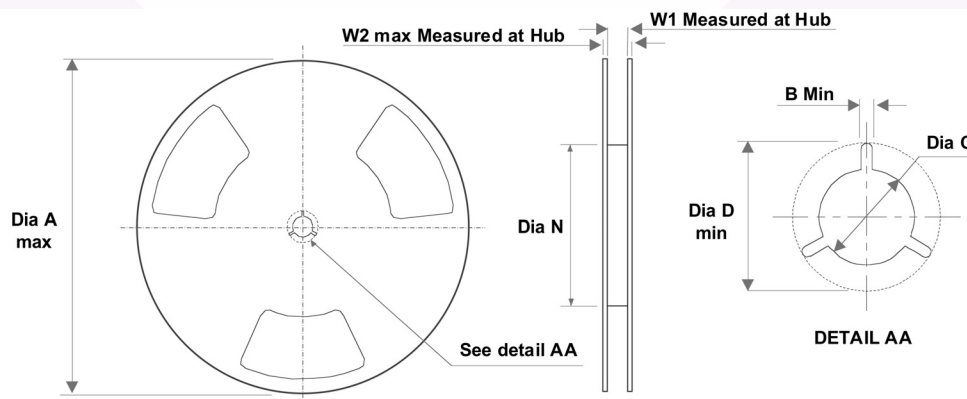
PKG. SIZE	DIM.Ao	DIM.Bo	DIM.Ko
3.5 X 4.5	3.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
3.0 X 3.0	3.3 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 4.5	2.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
2.5 X 3.5	2.8 ± 0.1	3.8 ± 0.1	0.9 ± 0.1
2.5 X 3.0	2.8 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 2.5	2.8 ± 0.1	2.8 ± 0.1	0.9 ± 0.1

DIMENSIONS ARE IN MILLIMETERS

NOTES: unless otherwise specified

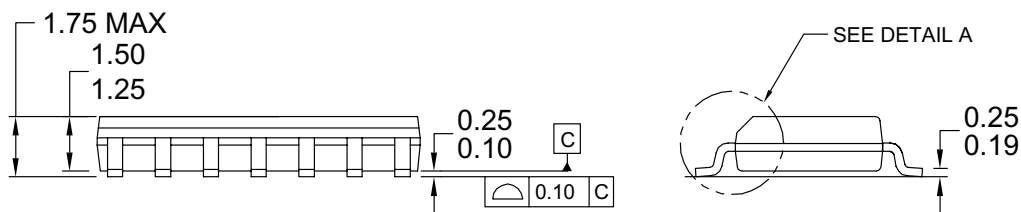
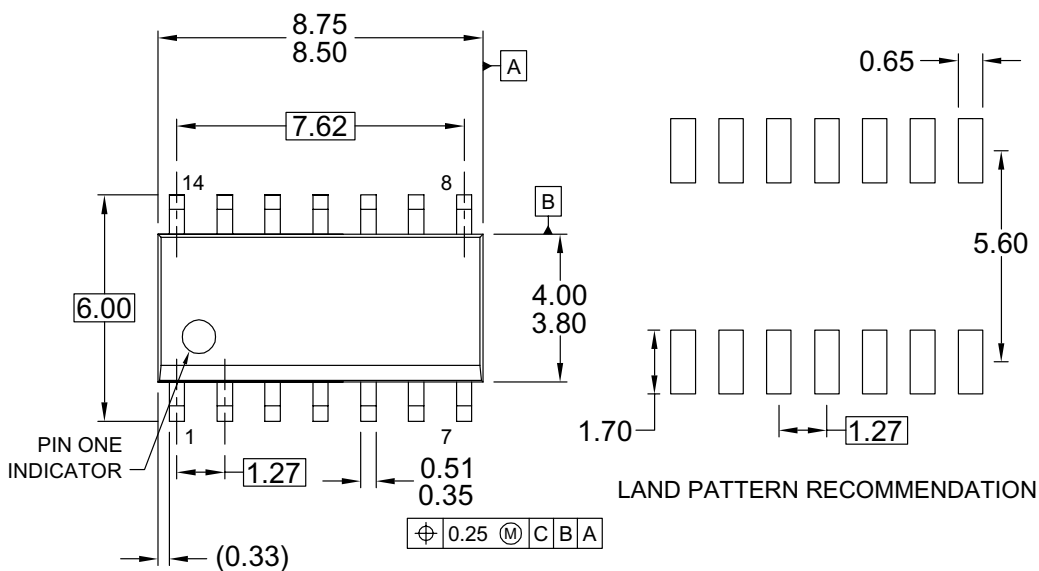
1. Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is $\pm 0.002[0.05]$ for these dimensions on all 12mm tapes.
5. Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Dimension in inches rounded.

Reel Dimensions inches (millimeters)



Tape Size	A	B	C	D	N	W1	W2
12mm	13.0 (330.0)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.488 (12.4)	0.724 (18.4)

Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

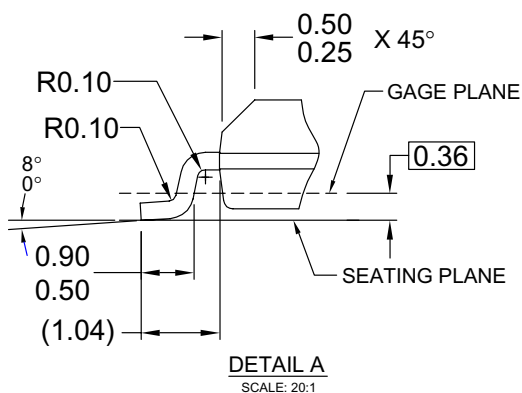


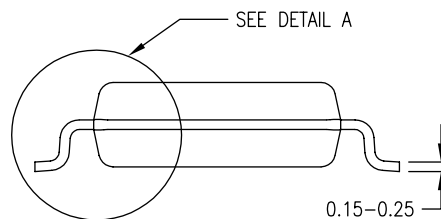
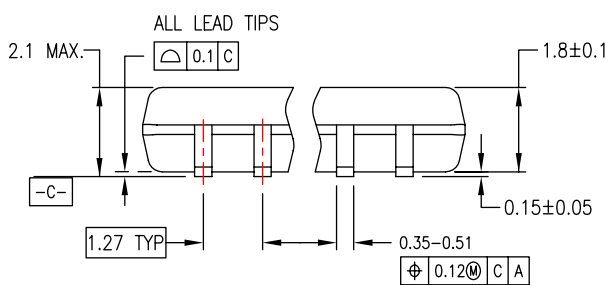
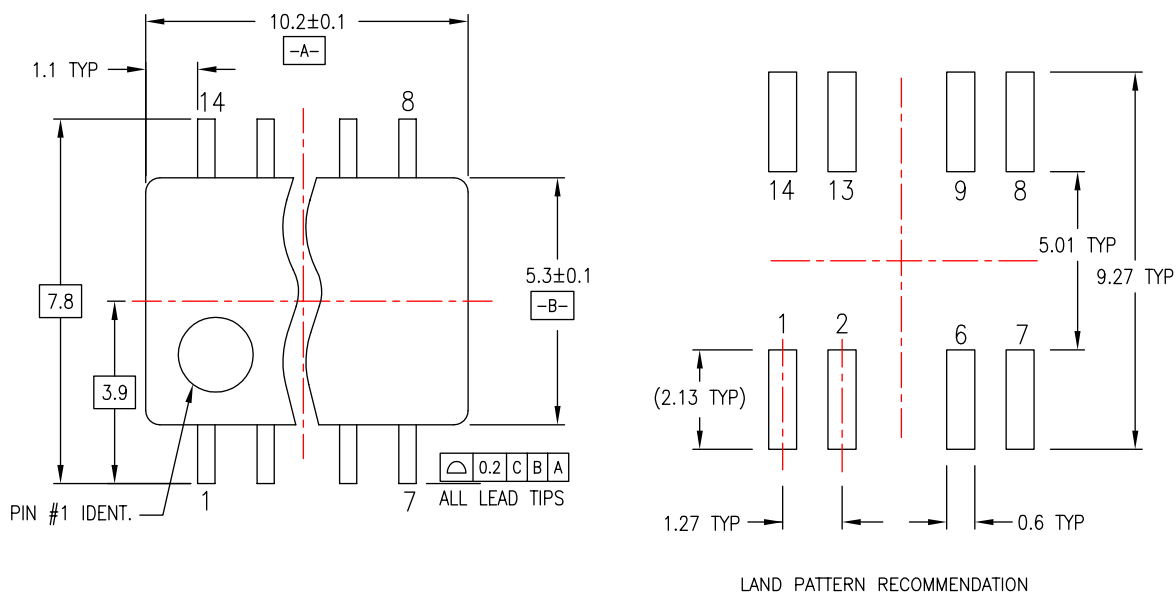
Figure 3. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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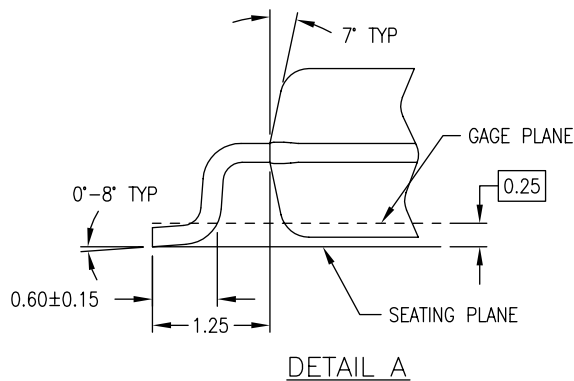
Physical Dimensions (Continued)



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

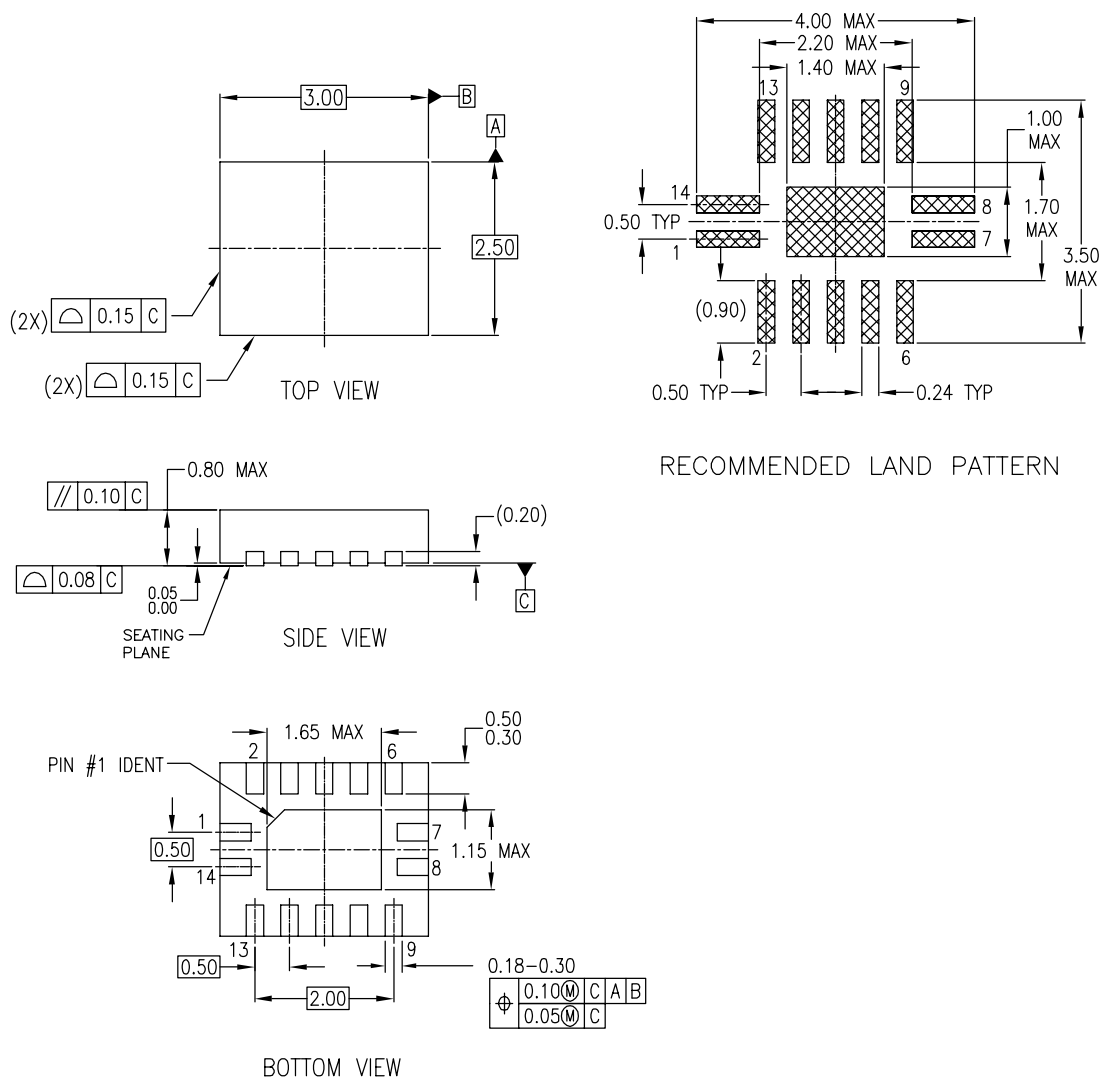
Figure 4. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued)



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP14ArevA

Figure 5. 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm

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| FAST® | OptoHiT™ | SuperSOT™-6 | VisualMax™ |
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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